

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Maxim S. Shatalov</td> <td>09/06/2012</td> </tr> <tr> <td>Rakesh Jain</td> <td>09/11/2012</td> </tr> <tr> <td>Jinwei Yang</td> <td>09/06/2012</td> </tr> <tr> <td>Michael Shur</td> <td>09/06/2012</td> </tr> <tr> <td>Remigijus Gaska</td> <td>09/06/2012</td> </tr> </tbody> </table>		Name	Execution Date	Maxim S. Shatalov	09/06/2012	Rakesh Jain	09/11/2012	Jinwei Yang	09/06/2012	Michael Shur	09/06/2012	Remigijus Gaska	09/06/2012
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<table border="1"> <tr> <td>Name:</td> <td>Sensor Electronic Technology, Inc.</td> </tr> <tr> <td>Street Address:</td> <td>1195 Atlas Road</td> </tr> <tr> <td>City:</td> <td>Columbia</td> </tr> <tr> <td>State/Country:</td> <td>SOUTH CAROLINA</td> </tr> <tr> <td>Postal Code:</td> <td>29209</td> </tr> </table>		Name:	Sensor Electronic Technology, Inc.	Street Address:	1195 Atlas Road	City:	Columbia	State/Country:	SOUTH CAROLINA	Postal Code:	29209		
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CORRESPONDENCE DATA													
<p>Fax Number: 5184490047 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 518-449-0044 Email: lcronk@hoffmanwarnick.com Correspondent Name: Hoffman Warnick LLC Address Line 1: 540 Broadway Address Line 2: 4th Floor Address Line 4: Albany, NEW YORK 12207</p>													
ATTORNEY DOCKET NUMBER:	SETI-0066												
NAME OF SUBMITTER:	John W. LaBatt												

OP \$40.00 13605007

Total Attachments: 6

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ASSIGNMENT OF PATENT APPLICATION

FOR GOOD AND VALUABLE CONSIDERATION,

We, the undersigned (each) have agreed and hereby agree to assign for good and valuable consideration, receipt of which is hereby expressly acknowledged, and do hereby sell, assign and transfer unto

Sensor Electronic Technology, Inc.

a corporation organized under the laws of the state of New York as Assignee, and its successors, assigns and legal representatives, the entire right, title and interest, for all countries in and to certain inventions relating to

Patterned Substrate Design for Layer Growth

described in a U.S. Provisional Application No. 61/531,440, filed on 6 September 2011, and in an application for Letters Patent of the United States, identified as Attorney Docket No. SETI-0066, at Hoffman Warnick LLC, 540 Broadway, 4th Floor, Albany, NY 12207, and the invention(s) and improvement(s) set forth therein, and any and all continuations, continuations-in-part, divisionals, and renewals of and substitutes for either or both of the applications for said Letters Patent, and all the rights and privileges under any and all Letters Patent that may be granted therefor in any country, and any reissues, or reexaminations, or extensions of said Letters Patent. We request that any and all Letters Patent for said inventions be issued to said Assignee, its successors, assigns and legal representatives, or to such nominees as it may designate.

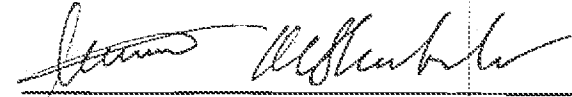
We agree that, when requested, we will, without charge to said Assignee but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable or convenient for securing and maintaining patents for said inventions in any and all countries and for vesting title thereto in said Assignee, its successors, assigns and legal representatives or nominees.

We authorize and empower the Assignee, its successors, assigns and legal representatives or nominees, to invoke and claim for any application for patent or other form of protection for said inventions filed by it or them, the benefit of the right of priority provided by the International Convention for the Protection of Industrial Property, as amended, or by any convention which may henceforth be substituted for it, and to invoke and claim such right of priority without further written or oral authorization from us.

We hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any assignment, consent to file or like document which may be required in any country for any purpose and more particularly in proof of the right of the Assignee or nominee to claim the aforesaid benefit of the right of priority provided by the International convention which may henceforth be substituted for it.

We covenant with the Assignee, its successors, assigns and legal representatives, that the rights and property herein conveyed are free and clear of any encumbrance, and that we have full right to convey the same as herein expressed.


IN WITNESS WHEREOF, we have hereunto signed our name(s) on the day and year set forth below.


Maxim S Shatalov

9/6/12
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Rakesh Jain

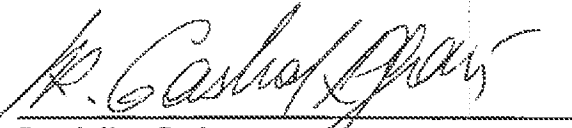
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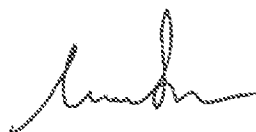
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